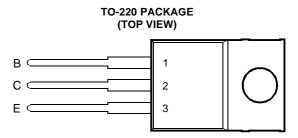
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- Rugged Triple-Diffused Planar Construction
- 4 A Continuous Collector Current
- Operating Characteristics Fully Guaranteed at 100°C
- 1000 Volt Blocking Capability



Pin 2 is in electrical contact with the mounting base.

MDTRACA

#### absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT		
Collector base voltage $(I_{-}, 0)$	TIPL791		850	V	
Collector-base voltage ( $I_E = 0$ )	TIPL791A	V <sub>CBO</sub>	1000	v	
Collector-emitter voltage ( $V_{RE} = 0$ )	TIPL791	M	850	V	
$Collector-entitler voltage (v_{BE} = 0)$	TIPL791A	V <sub>CES</sub>	1000	v	
Collector omitter veltage $(I_{-} = 0)$	TIPL791	M	400	V	
Collector-emitter voltage $(I_B = 0)$	TIPL791A	V <sub>CEO</sub>	450	v	
Emitter-base voltage	V <sub>EBO</sub>	10	V		
Continuous collector current			4	A	
Peak collector current (see Note 1)			8	A	
Continuous device dissipation at (or below) 25°C case temperature			75	W	
Operating junction temperature range	Тj	-65 to +150	°C		
Storage temperature range	T <sub>stg</sub>	-65 to +150	°C		

NOTE 1: This value applies for  $t_p \leq 10$  ms, duty cycle  $\leq 2\%.$ 



MAY 1989 - REVISED MARCH 1997

#### electrical characteristics at 25°C case temperature (unless otherwise noted)

l	PARAMETER			TEST C	ONDITIONS		MIN	TYP	MAX	UNIT
V <sub>CEO(sus)</sub>	Collector-emitter sustaining voltage	I <sub>C</sub> = 100	mA	L = 25 mH	(see Note 2)	TIPL791 TIPL791A	400 450			V
I <sub>CES</sub>	Collector-emitter cut-off current	$V_{CE} = 8$ $V_{CE} = 10$ $V_{CE} = 8$ $V_{CE} = 10$	00 V 50 V	$V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$	T <sub>C</sub> = 100°C T <sub>C</sub> = 100°C	TIPL791 TIPL791A TIPL791 TIPL791A			5 5 200 200	μA
I <sub>CEO</sub>	Collector cut-off current	$V_{CE} = 4$ $V_{CE} = 4$		$I_B = 0$ $I_B = 0$		TIPL791 TIPL791A			5 5	μA
I <sub>EBO</sub>	Emitter cut-off current	V <sub>EB</sub> =	10 V	I <sub>C</sub> = 0					1	mA
h <sub>FE</sub>	Forward current transfer ratio	V <sub>CE</sub> =	5 V	I <sub>C</sub> = 0.5 A	(see Notes 3 ar	nd 4)	20		60	
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	I <sub>B</sub> = (	0.2 A 0.5 A 1 A 1 A	$I_{C} = 1 A$ $I_{C} = 2.5 A$ $I_{C} = 4 A$ $I_{C} = 4 A$	(see Notes 3 ar T <sub>C</sub> = 100°C	nd 4)			0.5 1.0 2.5 5.0	V
V <sub>BE(sat)</sub>	Base-emitter saturation voltage	I <sub>B</sub> = (	0.2 A 0.5 A 1 A 1 A	$I_{C} = 1 A$ $I_{C} = 2.5 A$ $I_{C} = 4 A$ $I_{C} = 4 A$	(see Notes 3 ar T <sub>C</sub> = 100°C	nd 4)			1.0 1.2 1.4 1.3	V
ft	Current gain bandwidth product	V <sub>CE</sub> =	10 V	I <sub>C</sub> = 0.5 A	f = 1 MHz			12		MHz
C <sub>ob</sub>	Output capacitance	V <sub>CB</sub> =	20 V	$I_E = 0$	f = 0.1 MHz			110		pF

NOTES: 2. Inductive loop switching measurement.

3. These parameters must be measured using pulse techniques,  $t_p$  = 300  $\mu s,$  duty cycle  $\leq$  2%.

4. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

#### thermal characteristics

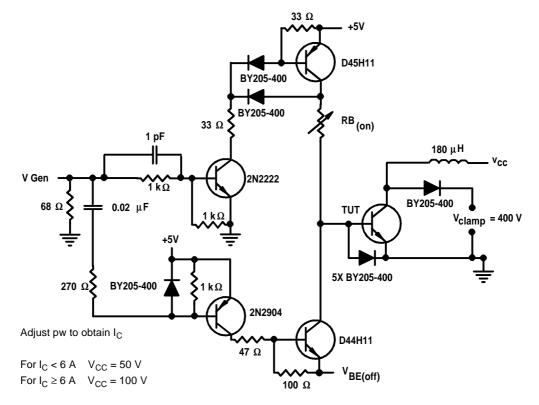
PARAMETER		MIN	TYP	MAX	UNIT
$R_{\thetaJC}$	Junction to case thermal resistance			1.66	°C/W

#### inductive-load-switching characteristics at 25°C case temperature (unless otherwise noted)

	PARAMETER		TEST CONDITION	NS <sup>†</sup>	MIN	TYP	MAX	UNIT
t <sub>sv</sub>	Voltage storage time						2	μs
t <sub>rv</sub>	Voltage rise time	$I_{C} = 4 A$ $V_{BE(off)} = -5 V$	I <sub>B(on)</sub> = 0.8A	(see Figures 1 and 2)			200	ns
t <sub>fi</sub>	Current fall time						100	ns
t <sub>ti</sub>	Current tail time						50	ns
t <sub>xo</sub>	Cross over time						200	ns
t <sub>sv</sub>	Voltage storage time	$I_{C} = 4 A$ $V_{BE(off)} = -5 V$	I <sub>B(on)</sub> = 0.8A T <sub>C</sub> = 100°C	(see Figures 1 and 2)			2.5	μs
t <sub>rv</sub>	Voltage rise time						400	ns
t <sub>fi</sub>	Current fall time						200	ns
t <sub>ti</sub>	Current tail time						50	ns
t <sub>xo</sub>	Cross over time						600	ns

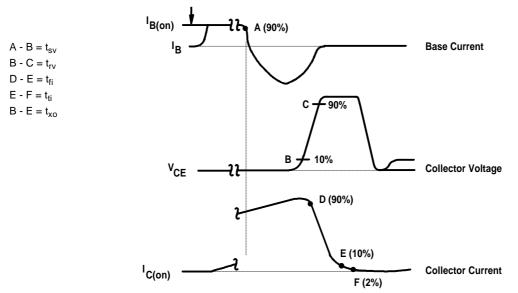
<sup>†</sup> Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

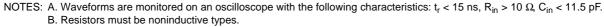
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### PARAMETER MEASUREMENT INFORMATION



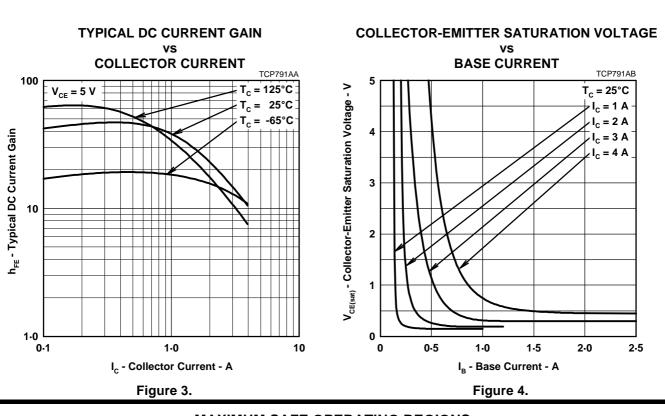






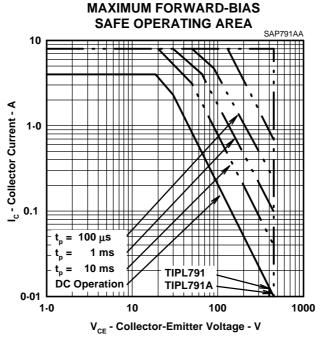


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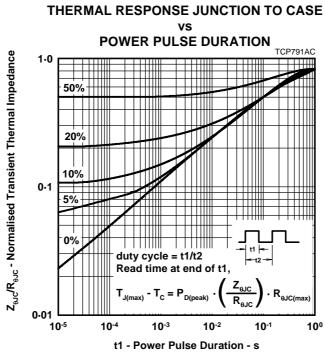
#### **TYPICAL CHARACTERISTICS**







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#### **THERMAL INFORMATION**

Figure 6.



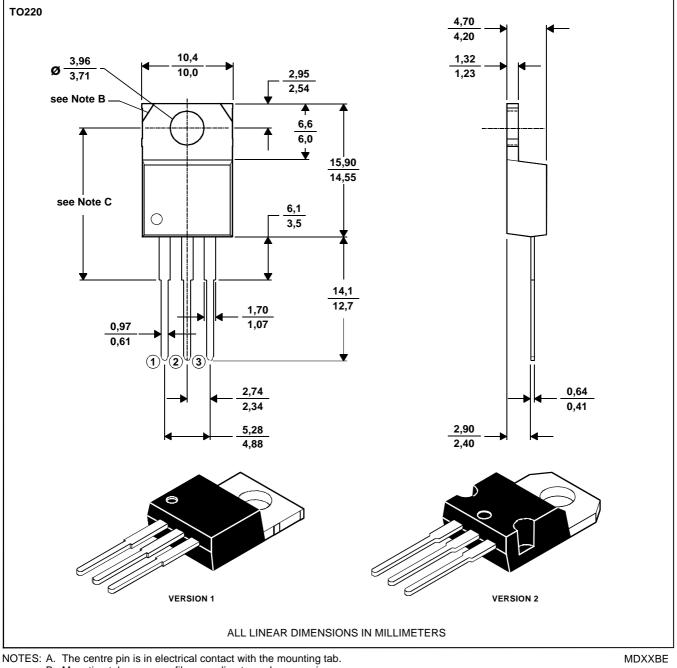
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### **MECHANICAL DATA**

### TO-220

### 3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



B. Mounting tab corner profile according to package version.

C. Typical fixing hole centre stand off height according to package version.

Version 1, 18.0 mm. Version 2, 17.6 mm.

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